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| Application Number | 10807873 |
| Filing Date | 2005-09-09 |
| First Named Inventor | Stasiak et al |
| Art Unit | |
| Examiner Name | |
| Attorney Docket Number | 200309781-1 |

U.S.PATENTS

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| | 1 | 5948621 | A | 1999-09-07 | Turner et al | |
| | 2 | 5776748 | A | 1998-07-07 | Singhvi | |

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| | 1 | 20030054342 | A1 | 2003-03-20 | Star et al | |
| | 2 | 20020119251 | A1 | 2002-08-29 | Chen et al | |
| | 3 | 20030032046 | A1 | 2003-02-13 | Duffy et al | |
| | 4 | 20050118338 | A1 | 2005-06-02 | Steve et al | |

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|--------------------|---------|---|--------------------------|
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| | 2 | Pfeiffer K et al, "Polymer stamps for nanoimprinting", Microelectronic Engineering, V 61-62, July 2002, pp 393-398 | <input type="checkbox"/> |
| | 3 | Schift H et al, "Chemical non-patterning using hot embossing lithography", Microelectronic Engineering, V. 61-62, July 2002, pp 423-428 | <input type="checkbox"/> |
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